

IMAPS August 2017 newsletter Get ready for the next events!



Hello IMAPS-UK Members, Friends & Supporters

.... August has carried on that wonderful weather that we know and love, a typical English Summer ... warm then wet followed by hot or cold and of course wind and rain.

This sounds just like the conditions that we put our electronics systems through to get reliability data ... which of course allows me to remind you to book for the "RELPACK" Conference (Reliability Engineering for Electronic Packaging) being organised at STFC Daresbury Labs on 30th November. (see below)

EVENT News ...

THE Packaging Workshop - sponsored by 

and supported by 

The Packaging Workshop (28 September) is now already fully booked and there is a waiting list this is a reminder for those who have missed being able to book too let me know if you want us to repeat it at the end of this year or early next year.

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Reliability Engineering for Electronic Packaging

The "RELPACK" Conference

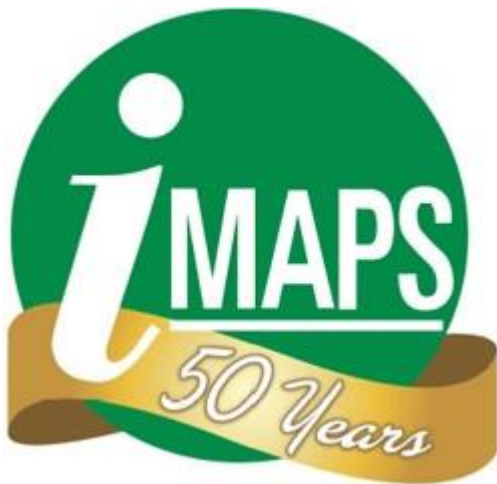
.... is the final IMAPS-UK event for 2017 (at the moment !). It is on 30 November at STFC Daresbury Labs. Places are already being booked so we think this topic is generating lots of interest as well. The programme and full details are on the website - book your place early to avoid missing out.

[Click HERE for more information on this event.](#)

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IS PACKAGING MORE THAN MOORE ?



We think so and after 50 Years since ISHM was founded and later became iMAPS ... much has changed and much "moore" will change in the future ...

The 2018 Microtech conference, the annual conference of iMAPS-UK marks

50 years for the International Microelectronics Assembly and Packaging Society in UK – and we're celebrating! On 9 April, the evening before the IMAPS-UK MicroTech , (our annual Conference and AGM), we will have a Gala Dinner event at the same site as the conference - being held on 10 April 2018 at the Windsor Conference Centre at the Royal Holloway College in Egham Surrey, near London. so do book to join us at this special event,

The Gala Dinner will feature Company and Individual of the Year Awards, plus a keynote providing an insight into the future Technologies and Trends and a special presentation looking at the development of IMAPS-UK and the various microelectronics packaging technologies we see today.

MOORE THAN PACKAGING: 50 Years Gone; 50 Years On!

The Society's 50th Annual Conference on the 10th April, is also at the prestigious Royal Holloway Windsor Conference Centre in Egham Surrey.

Continuing the events theme "MOORE THAN PACKAGING: 50 Years Gone; 50 Years on", the Conference will bring together experts from across the microelectronics sector to discuss the latest technologies and developments, as well as providing a platform to highlight current commercial opportunities.

Sessions will cover: Process & Technologies, Materials, Applications and Trends, followed by a Panel Session looking at the future direction, challenges and technologies our industry faces.

BOOK THE DATES NOW - Workshops followed by a Gala Dinner on **9 April** and the Conference/AGM on **10 April**.

There are opportunities for Exhibitors, Sponsors and Speakers

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21ST EUROPEAN
MICROELECTRONICS AND PACKAGING
CONFERENCE (EMPC) & EXHIBITION

EMPC (Warsaw) – 10-13 September.

For the first time the IMAPS Europe "EMPC" conference is organized in eastern part of Europe. This gives an extra opportunity to bring together the entire microelectronics supply chain, technical and marketing professionals from all parts of Europe. The variety of sessions offers the possibility to enhance professional development, technical knowledge/skills and career progression. Furthermore, the industrial exhibition will highlight the latest products and service applications of value to the electronics community.

Go to <http://www.empc2017.pl/> for full details.

An Invitation for IMAPS-UK members

Flexible Hybrid Electronics Manufacturing - New approaches to the production of flexible smart systems

**EPSRC Centre for Large Area Electronics and Imperial College
Workshop – Tuesday 12 September at Imperial College London**

“Flexible Hybrid Electronics combine the flexibility, thinness and lightness of large area electronics with the processing power of silicon to open up a broad range of new applications in the internet of things, smart buildings, healthcare, product packaging, retail and consumer electronics. Significant technical challenges arise in the integration of hybrid systems that are flexible and yet include small islands of rigid electronics, such as a silicon chip or a passive component.

The EPSRC Centre for Large Area Electronics and Imperial College London are organising a workshop event on Tuesday 12 September at Imperial College starting at 12:00 to present results of their research work and ideas for future flexible hybrid electronics manufacturing. If you are interested in attending this free, invitation only event, could you e-mail: info@largeareaelectronics.org?”

SOME OTHER EVENTS >>>>>

[PEUK: Thermal Management Workshop](#)

3M, Bracknell - Sept 21

Market requirements for power electronics and RF power devices are driver higher power densities and the need to operate in higher temperature environments. As a result, thermal management of devices and systems is a key design and manufacturing challenge.



The aim of this workshop is to bring together the power electronics and power RF communities to discuss trends and directions in device and systems thermal management to encourage best practice and the development of new supply chain collaborations in R&D.

Topics within scope include:

- The integration of new high performance materials into systems for thermal management and harsh environment performance.
- Active cooling and thermal management designs and configuration in power electronics and power RF systems
- Passive cooling mechanisms and designs.
- Thermal modelling and characterisation
- [Register here](#)



Centre for Power Electronics - Wide Band-Gap Event 2017

Realising the True Potential of Wide Band-Gap Power Electronics

Wednesday 11 October 2017

Jubilee Conference Centre

University of Nottingham

This **free** event will explore the future direction of Wide Band-Gap Power Electronics. It will be of interest to those working in the field, whether you are from

academia or from industry.

The agenda will include:

- Highlights of previous Centre for Power Electronics research in this field .
- An introduction to our work in this area for the next three years.
- Updates on the latest developments from Power Electronics UK, the Compound Semiconductor Applications Catapult and leading semiconductor manufacturers.
- The Future Power Challenge, a competition to stimulate university / industry research.
- An overview of the relevant strategic initiatives relating to Wide Band-Gap Power Electronics
- An opportunity to take part in cross-sector workshops to provide input into the industrial strategy for UK Power Electronics.

[Register your interest](#)

Places are limited and in the event of oversubscription representation from individual organisations will be limited accordingly.

The deadline for registration is **8 September 2017**

We will confirm your place by email by **12 September 2017**

The Power Electronics Expo UK

This event runs 15th March 2018 at the International Centre, Telford in the West Midlands, a major hub of the UK's high tech industrial sector. See www.powerelectronicsexpo.co.uk

Power Electronics is driving significant change across a range of industry sectors including the renewable energy generation, energy networks, transportation and industrial processes arenas. The event will provide a unique opportunity for businesses in the field to showcase their latest products, technologies and services. Should you wish to reserve space to exhibit, the organisers are offering a 15% discount on the price of a single space until the end of July.

"Electronics Packaging and Test for Future Mobility"

The registration for the SEMICON Europa 2017 is now open. This event is

on at the same time as Productronica in Munich. It will also include the Advanced Packaging Conference ... which this year is about "Electronics Packaging and Test for Future Mobility"see [here](#) for the full details:

SEMI have offered a 10% discount for IMAPS-UK members who wish to attend this conference. Please contact me at the secretariat for the discount code to use when booking your place.

As a further bonus, all registered conference attendees will receive in their confirmation a promo code to get free access to the Productronica show floor – separate registration is mandatory.

Industry news ...

An event from Techworks (Formerly NMI)

Open Innovation Day ... with Thales (Grenoble)

If you are start-up or SME looking to present your creative solution for a safer world to one of the world players in smart technology, the Open Innovation Day with Thales on October 19 might be an excellent opportunity!

For more information : <http://www.minalogic.com/fr/evenement/open-innovation-day-thales>

iNEMI Need Your Input ...

Survey to Assess Polymer Outgassing Metrology

iNEMI is conducting an industry survey to assess current electronics industry practices for measuring polymer outgassing. Understanding the characteristics of polymer outgassing from the materials and packaging used in electronics is critical to predicting failures and potential causes of those failures. There are several techniques and metrologies to analyze outgassing.

By participating in this survey, you will help us identify current practices and future direction of polymer outgassing metrology in the industry. In addition, survey results will be used to define project objectives and a workplan for the

proposed iNEMI project, Next Generation of Non-Hermetic Package Reliability Metrology. If you are interested in getting involved in this project, contact Masahiro Tsuruya.

If you are not the right person in your organization to take this survey, please forward this to the correct contact. Also feel free to forward this to anyone at another organization that you think may want to respond.

Markets ... According to Analysts Research and Markets,

Innovations in Silicon Photonics

The silicon photonics (SiP) is an emerging industry with a high level of collaboration between key stakeholders. SiP technology integrates complementary metal-oxide semiconductor (CMOS), three-dimensional (3D) integration, and fiber optic communication technologies. The objective of the SiP technology is to leverage CMOS manufacturing capabilities to fabricate and manufacture photonic devices.

For more information please click on:

<https://www.researchandmarkets.com/publication/mcyz5fl/4330306>

Global Silicon Photonics Market, Analysis & Forecast, 2017-2022

Silicon photonics market is expected to show a remarkable growth in the next 5 years. The factors driving the growth of this market include price, capability, and size. As the price of silicon photonics technology is constantly falling, its demand is extensively increasing in all the verticals including healthcare, telecommunication and defense among others. Over the years, major players are showing their interest in silicon photonics market. Players like Intel Corporation, Cisco Systems, Inc., IBM Corporation and Juniper Networks, Inc. among others are investing extensively in silicon photonics market in order to improvise their products as well as to capture a major market share.

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More about iMAPS-UK

iMAPS-UK is not just about events we have over 150 members. many who are expert in specialist areas of microelectronics packaging, interconnection and assembly. We are pleased to see that more of our members are using the "secretariat" office as a focal point to find out technical information, answer technical queries and help source products and services. This brokerage service is part of what you pay your membership fee for, so please feel free to keep the questions coming.....

Membership of iMAPS-UK

Not a Member ? Join NOW and enjoy more Any new members joining from now onwards will be enrolled as members for the rest of 2017 and all of 2018

Remember IMAPS-UK membership key benefits are:

- Member to member exchange
- Expand your contacts
- Regular newsletters and bulletins
- Discounted registration at IMAPS events globally
- 50 (free) downloads from the "iMAPSource" Knowledge library
- Receive Advancing Microelectronics magazine
- Free affiliate membership of IMAPS North America
- A vote at the IMAPS-UK AGM

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Thanks for reading this - enjoy the rest of the "summer"

Kind regards

Andy Longford - IMAPS-UK Secretariat

This e-mail newsletter has been sent to you by
IMAPS-UK Secretariat - Andy Longford - on
Thursday 17 August 2017



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